

Tool ID: 218
Tool Location: 114

Equipment Information Sheet
Anatech Resist Strip

Manager: Aaron Windsor
Backup: Christopher Alpha

607-254-4831
607-254-4913

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- No unusual hazards during normal operation

USAGE RESTRICTIONS

- No buddy system restrictions

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- Maximum 2 hour reservation block at any time
- Maximum 6 hours reserved in advance at any time
- No consecutive reservations by the same person, group, or company
- You may use any amount of unreserved time
- Additional restrictions may be imposed as ne

MATERIALS COMPATIBILITY CATEGORY

Tool Category 4: Glass and Metal Categories	
Allowed	Not Allowed
Tool category 1/1E, 2, and 3 materials	
Silicon Based Substrates and Films	No CNF Class A metals
III/V compound Semiconductors	No Exposed CNF Group B metals- <i>metals can be buried/covered with staff approval</i>
Glass Substrates	Cannot be used as an etch stop
PECVD and ALD Films	
Buried Class B Metals with approval	
Organic/Bio Materials prepped w/o Salt Buffers	
Cured organics and baked Photoresist	No High Vapor pressure materials

High Vapor Pressure Metals and Compoundsare materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Silicon wafers, III-V wafers, glass, and ceramic only
- No plastic or metal
- No Cadmium, no Zinc

Last Updated: 02/15/2021